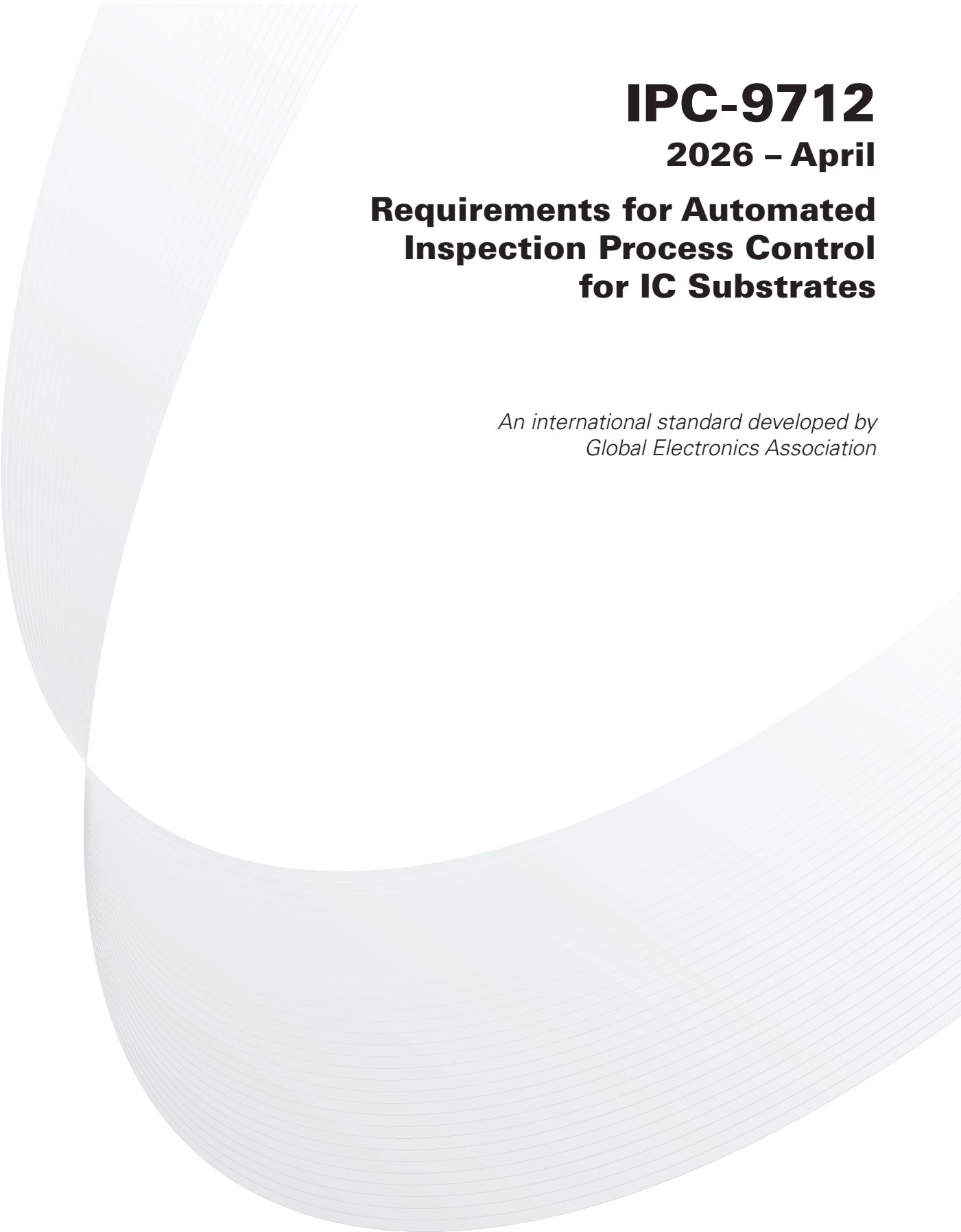




IPC-9712

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Requirements for Automated Inspection Process Control for IC Substrates

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Requirements for Automated Inspection Process Control for IC Substrates

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Developed by the Automated Inspection for IC Substrates Process Control Standard Task Group (7-25b) of the Process Control Management Committee (7-20) of IPC

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Contact:

Global Electronics Association
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Process Control Management Committee

Chair

Tiberiu Baranyi
Flextronics Romania SRL

Automated Inspection for IC Substrates Process Control Standard Task Group

Chair

Feng Xue
IBM Infrastructure

Sherlock A-Team

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Stephanie Allard
IBM Canada Limited

Sylvain Pharand
IBM Canada Limited

Bertram Ren
AT&S (Chongqing) Company Ltd.

Feng Xue
IBM Infrastructure

Charlie Zhu
CyberOptics

Automated Inspection for IC Substrates Process Control Standard Task Group

Shobhit Agrawal
Keysight Technologies

Stephanie Allard
IBM Canada Limited

Michael Allison
Northrop Grumman

Jacynth Anderson
Lockheed Martin Missile & Fire Control

Tiberiu Baranyi
Flextronics Romania SRL

Elizabeth Cain
TTM Technologies Advanced Technology Center

Zhiman Chen
ZHUZHOU CRRC TIMES ELECTRIC CO., LTD

Francesco Di Maio
Francesco Di Maio Consulting

Michael Engel
Mercedes-Benz AG

Symon Franklin
Custom Interconnect Ltd

James Gatherer
Intel Corporation

Zhao Guoqing
Changsha ZTE Intelligence Technology Co, Ltd

Sean Hensarling
SpaceX

Meghua Jiang
CyberOptics

Tianlei Jiang
ZTE Nanjing Co., Ltd.

Mingu Kang
Intek-Plus

Jacob Klotz
Calumet Electronics Corp.

Peng Li
ZTE Corporation

Thomas Marktscheffel
Patrick McComber
TTM Technologies, Inc.

Cibi Palaniappan
Cibi Palaniappan

Jackson Perry
Amphenol

Sylvain Pharand
IBM Canada Limited

Michah Pledger
Pledger Resources, LLC

Bertram Ren
AT&S (Chongqing) Company Ltd.

Hualiang Shi
Meta

Patrick Smith
Cirexx International, Inc.

Muthukrishnan Srinivasan
Caterpillar India Private Limited

Michael Tan
Intel Corporation

Audra Thurston
Calumet Electronics Corp.

Xing Tong
SAIC

Frank Uibel
Uibel Consulting

E. Jan Vardaman
TechSearch International Inc.

Sivakumar Vijayakumar
Keysight Technologies

Grant Wachtel
nScrypt Inc.

Udo Welzel
Robert Bosch GmbH

Raymond Whittier
BAE Systems

Nicholas Wilson
Northrop Grumman Corporation

Feng Xue
IBM Infrastructure

Charlie Zhu
CyberOptics

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